

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6560811

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MICHAEL EDLEY	01/26/2021
XINGHUA SUN	01/25/2021
YEN-TIEN LU	01/25/2021
ANGELIQUE RALEY	01/26/2021
HENAN ZHANG	01/26/2021
HIROYUKI SUZUKI	02/16/2021
SHAN HU	01/28/2021
RECEIVING PARTY DATA	
Name:	TOKYO ELECTRON LIMITED
Street Address:	AKASAKA BIZ TOWER
Internal Address:	3-1 AKASAKA 5-CHOME
City:	MINATO-KU, TOKYO
State/Country:	JAPAN
Postal Code:	107-6325
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17180077
CORRESPONDENCE DATA	
Fax Number:	(972)732-9218
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(972) 732-1001
Email:	DOCKETING@SLATERMATSIL.COM
Correspondent Name:	SLATER MATSIL, LLP
Address Line 1:	17950 PRESTON ROAD
Address Line 2:	SUITE 1000
Address Line 4:	DALLAS, TEXAS 75252
ATTORNEY DOCKET NUMBER:	TEL-190555US02
NAME OF SUBMITTER:	SHANNON TROTTER
SIGNATURE:	/Shannon Trotter/

PATENT

DATE SIGNED:

02/19/2021

Total Attachments: 18

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**DECLARATION (37 CFR 1.63) AND ASSIGNMENT FOR
NONPROVISIONAL UTILITY OR DESIGN PATENT APPLICATION**

Title of Invention: RADIATION OF SUBSTRATES DURING PROCESSING AND SYSTEMS
THEREOF

As a below named inventor, I hereby declare that:

This declaration and assignment is directed to:

The attached application having a docket number and title identified above, or
 United States application number or PCT international application number
_____ filed on _____.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the
above-identified application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information
known to me to be material to patentability as defined in 37 C.F.R. § 1.56.

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18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

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the above-identified patent application.

Assignee: The Assignee is **Tokyo Electron Limited**, a corporation of Japan having a place of business at
Tokyo, Japan (herein referred to as the "ASSIGNEE"). The term "ASSIGNEE" used herein includes
successors, legal representatives, and assigns of the ASSIGNEE. The ASSIGNEE desires to acquire the
entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications
and patents obtained from the Invention.

As an undersigned inventor, I hereby assign to the ASSIGNEE my entire worldwide right, title, and
interest in and to the Invention, the above-identified United States patent application, and any and all other
patent applications and patents for the Invention which may be applied for or granted therefrom in the United
States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues,
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authorize and request the Director of the United States Patent and Trademark Office to issue any United
States Patent, granted for the invention, to the ASSIGNEE, and I authorize and request foreign patent
authorities to issue any foreign patent, granted for the Invention, to the ASSIGNEE. The entire worldwide
right, title, and interest in and to the same to be held and enjoyed by the ASSIGNEE, to the full end of the
terms for which any and all such patents may be granted, as fully and entirely as would have been held and
enjoyed by the undersigned had this Assignment not been made. I agree to execute any and all documents
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Assignment any further identification (including, but not limited to, patent application number and filing date) which may be necessary or desirable for recording this Declaration and Assignment.

(1) Legal name of Inventor: Michael Edley
 Inventor's Signature: *Michael Edley* Date: 1/26/21
 Residence City/State/Country: Philadelphia PA USA
 Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South
255 Fuller Rd., Suite 214, Albany, NY, 12203 United States
 Citizenship: United States

(2) Legal name of Inventor: Xinghua Sun
 Inventor's Signature: _____ Date: _____
 Residence City/State/Country: _____
 Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South
255 Fuller Rd., Suite 214, Albany, NY, 12203 United States
 Citizenship: _____

(3) Legal name of Inventor: Yen-Tien Lu
 Inventor's Signature: _____ Date: _____
 Residence City/State/Country: _____
 Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South
255 Fuller Rd., Suite 214, Albany, NY, 12203 United States
 Citizenship: _____

(4) Legal name of Inventor: Angelique Raley
 Inventor's Signature: _____ Date: _____
 Residence City/State/Country: _____
 Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South
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 Citizenship: _____

(5) Legal name of Inventor: Henan Zhang
 Inventor's Signature: _____ Date: _____
 Residence City/State/Country: _____
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 Residence City/State/Country: _____
 Mailing Address: c/o Tokyo Electron America, Inc., NanoFab 300 South 255 Fuller
Rd., Suite 214, Albany, NY, 12203 United States
 Citizenship: _____

(7) Legal name of Inventor: Shan Hu
Inventor's Signature: _____ Date: _____
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 Residence City/State/Country: _____
 Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South
 255 Fuller Rd., Suite 214, Albany, NY, 12203 United States
 Citizenship: _____

(2) Legal name of Inventor: Xinghua Sun
 Inventor's Signature: [Signature] Date: 01/25/2021
 Residence City/State/Country: Clifton Park, NY, USA
 Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South
 255 Fuller Rd., Suite 214, Albany, NY, 12203 United States
 Citizenship: China

(3) Legal name of Inventor: Yen-Tien Lu
 Inventor's Signature: _____ Date: _____
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 Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South
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 Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South
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 Citizenship: _____

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 Citizenship: _____

(3) Legal name of inventor: Yen-Tien Lu
 Inventor's Signature: [Signature] Date: 1/25/2021
 Residence City/State/Country: Hillsboro, OR, USA
 Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South
 255 Fuller Rd., Suite 214, Albany, NY, 12203 United States
 Citizenship: Taiwan

(4) Legal name of inventor: Angslique Raley
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Citizenship: _____

(4) Legal name of Inventor: Angelique Raley
Inventor's Signature: Angelique Raley Date: 1/26/2021
Residence City/State/Country: _____
Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South
255 Fuller Rd., Suite 214, Albany, NY, 12203 United States
Citizenship: FRANCE

(5) Legal name of Inventor: Henan Zhang
Inventor's Signature: [Signature] Date: 01/26/2021
Residence City/State/Country: Clifton Park / NY / US
Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South
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Inventor's Signature: _____ Date: _____
Residence City/State/Country: _____
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255 Fuller Rd., Suite 214, Albany, NY, 12203 United States
Citizenship: _____

(6) Legal name of Inventor: Hiroyuki Suzuki
Inventor's Signature: Hiroyuki Suzuki Date: 02.10.21
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(7) Legal name of Inventor: Shan Hu
Inventor's Signature: _____ Date: _____
Residence City/State/Country: _____
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255 Fuller Rd., Suite 214, Albany, NY, 12203 United States
Citizenship: _____

**DECLARATION (37 CFR 1.63) AND ASSIGNMENT FOR
NONPROVISIONAL UTILITY OR DESIGN PATENT APPLICATION**

Title of Invention: RADIATION OF SUBSTRATES DURING PROCESSING AND SYSTEMS
THEREOF

As a below named inventor, I hereby declare that:

This declaration and assignment is directed to:

The attached application having a docket number and title identified above, or
 United States application number or PCT international application number
_____ filed on _____.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the above-identified application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 C.F.R. § 1.56.

I hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Assignor(s): The Assignor(s) is/are the undersigned inventor(s). The inventor(s) named below has/have made certain inventions, improvements, and/or discoveries (herein referred to as the "Invention") disclosed in the above-identified patent application.

Assignee: The Assignee is **Tokyo Electron Limited**, a corporation of Japan having a place of business at **Tokyo, Japan** (herein referred to as the "ASSIGNEE"). The term "ASSIGNEE" used herein includes successors, legal representatives, and assigns of the ASSIGNEE. The ASSIGNEE desires to acquire the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents obtained from the Invention.

As an undersigned inventor, I hereby assign to the ASSIGNEE my entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefrom in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, I hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Patent, granted for the invention, to the ASSIGNEE, and I authorize and request foreign patent authorities to issue any foreign patent, granted for the invention, to the ASSIGNEE. The entire worldwide right, title, and interest in and to the same to be held and enjoyed by the ASSIGNEE, to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made. I agree to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, for the ASSIGNEE, whenever requested by the ASSIGNEE.

As an undersigned inventor, I acknowledge prior and ongoing obligations to sell, assign, and/or transfer my rights in the Invention to the ASSIGNEE. I have not sold, assigned, or otherwise transferred my rights in the Invention to another, and I am under no obligation to sell, assign, or otherwise transfer my rights in the Invention to another. I also hereby grant the ASSIGNEE, the right to insert in this Declaration and

Assignment any further identification (including, but not limited to, patent application number and filing date) which may be necessary or desirable for recording this Declaration and Assignment.

(1) Legal name of Inventor: Michael Edley
Inventor's Signature: _____ Date: _____
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Citizenship: _____

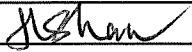
(2) Legal name of Inventor: Xinghua Sun
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(3) Legal name of Inventor: Yen-Tien Lu
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(4) Legal name of Inventor: Angelique Raley
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(5) Legal name of Inventor: Henan Zhang
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(6) Legal name of Inventor: Hiroyuki Suzuki
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(7) Legal name of Inventor: Shan Hu
Inventor's Signature:  Date: 1/28/2021
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